

Title (en)
ELECTRONIC MOLDING COMPOSITION AND METHOD

Title (de)
ELEKTRONIKFORMMASSE UND -VERFAHREN

Title (fr)
COMPOSITION ET PROCÉDÉ DE MOULAGE ÉLECTRONIQUE

Publication
EP 2024415 A1 20090218 (EN)

Application
EP 06759418 A 20060510

Priority
US 2006017952 W 20060510

Abstract (en)
[origin: WO2007130063A1] A curable molding composition is provided having a binder system and a filler system. The molding composition is useful as an electronic material composition for electronic devices.

IPC 8 full level
C08G 65/48 (2006.01); **C08K 9/06** (2006.01)

CPC (source: EP)
C08G 65/485 (2013.01); **C08L 71/126** (2013.01); **C08G 2650/04** (2013.01); **C08K 9/06** (2013.01)

Citation (search report)
See references of WO 2007130063A1

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DOCDB simple family (publication)
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